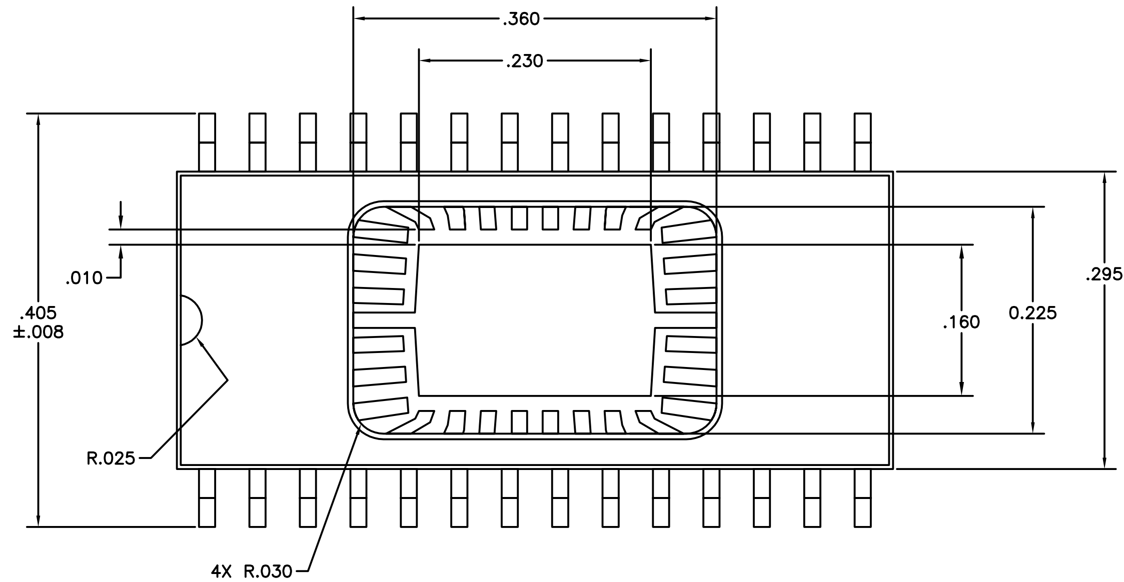
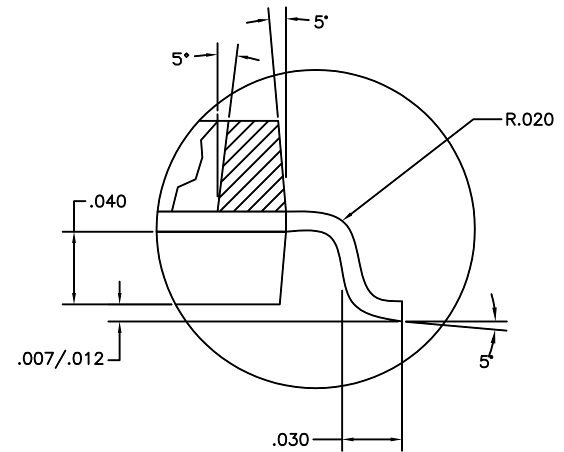
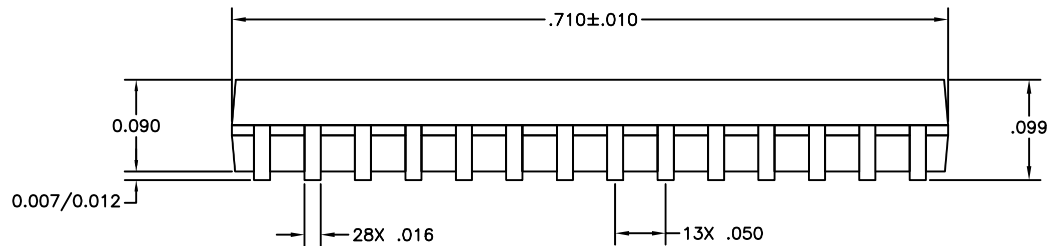
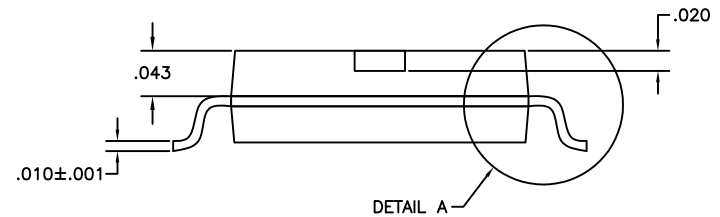
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10793	11/02/06	PRODUCTION RELEASE	D.BENANDO





DETAIL A
SCALE: 2/1





NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, FH 194.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: .230" x .160".

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ±---
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY C. CRUZ DATE 11/01/06
APP BY P. FLASKERUD DATE 11/01/06
CUSTOMER ---

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28 Lead 300 mils
SOIC Open-Pak

SIZE A | PART NO. SOIC300-28-OP-01 | REV 4
SCALE NONE | CAD FILE SOIC300-28-OP-01-R4.DWG | SHEET 1 OF 1